



Laird™ Tpli™ 210FG

Tpli™ 200 is a premium gap filler. A unique blend of boron nitride and silicone produce the highest performing interface pad. Tpli 200's exceptional combination of high thermal conductivity and compliancy generate unmatched thermal resistances in a gap filling interface material. Tpli 200 absorbs shock and relieves stresses, thus minimizing potential damage to components. Tpli 200 is electrically insulating, stable from -45°C to 200°C, and meets UL 94 HB rating.

TECHNICAL DATA SHEET | (EFFECTIVE 24FEB25)

Laird™ Tpli™ 210FG			
PHYSICAL PROPERTY	TEST METHOD	UNIT	VALUE
Construction & Composition		-	Boron nitride filled silicone sheet
Color		-	Varies by thickness
Thickness Range		mm in	0.25 - 5.08 0.010 - 0.20
Thickness Tolerance		%	10
Thermal Conductivity	ASTM D5470	w/mk	6.0
Density	Helium Pyncometer	g/cc	1.4
Hardness	ASTM D2240	Shore 00	70
Outgassing TML	ASTM E595	%	0.46
Outgassing CVCM	ASTM E595	%	0.15
Temperature Range		°C	-45 to 200
Rth @ 40 mils, 10 psi, 50°C	ASTM D5470 (modified)	°C-in²/w	0.25
Dielectric Constant @ 10GHz	ASTM D150	-	3.2
UL Flammability	UL 94	-	HB
Volume Resistivity	ASTM D257	ohm-cm	5 × 10 ¹³